

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2426	257/659,660,e23.114.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:12
L2	5046	438/106,127.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:17
L3	7409	1 2	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:18
L4	148087	(method process) and (encapsula\$4 seal\$3) and (substrate carrier board pcb) and (chip die (semiconductor near1 (device element)) and ((metal near1 (cover layer cap)) with ((back (non adj active)) near side) with second))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:26
L5	3001	3 and 4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:25
L6	164	5 and titanium and copper and (sawing singulat\$3 dicing cutting)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:27
L7	0	6 and nermetical\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:27
L8	31	6 and hermetical\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:32
L9	66	STELZL-A STELZL-ALOIS	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:31
L10	598	KRUEGER-H KRUEGER-HANS	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:32
L11	616	9 10	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:32

EAST Search History

L12	29	11 and hermetical\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/04/27 01:32
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